

High-Silicon Steel Sheet by Single Stage Shear-Based Processing

DE-EE0007868

Purdue University/M4 Sciences/PNNL

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Overview

Project Title: *High-Silicon Steel Sheet by Single Stage Shear-Based Processing*

Timeline:

Project Start Date: 06/15/2017
Budget Period End Date: 06/30/2019
Project End Date: 12/31/2020

AMO MYPP Connections:

- Next Generation of Electric Machines II- Key Enabling Technologies
- Low Loss Electrical Steel Manufacturing
- Improve electric motor efficiency;
- Increase US manufacturing productivity and efficiency

Barriers and Challenges:

- Low workability of high-Si steels
- Long lead-times (materials/equipment/tooling)
- Paradigm shift in materials processing

Project Budget and Costs:

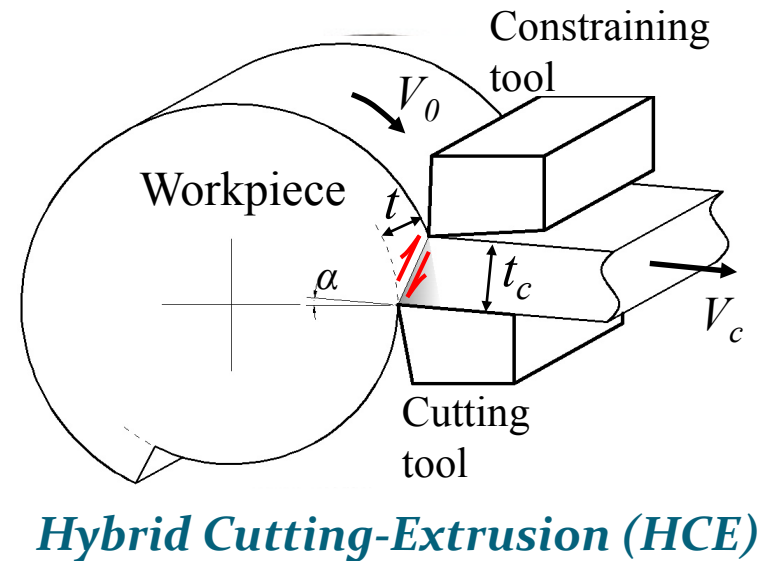
Budget	DOE Share	Cost Share	Total	CS %
Overall Budget	\$1,500,000	\$179,147	\$1,679,148	10.7%
Approved Budget (BP-1)	\$686,240	\$93,955	\$780,195	12.0%
Costs as of 3/31/19	\$653,286	\$88,578	\$741,863	11.9%

Project Team and Roles:

- ***Purdue:*** process development and characterization
- ***M₄ Sciences:*** machine/process design
- ***PNNL:*** sheet characterization
- ***Seco Tools:*** tooling development
- ***Strategic Partners***

Project Objective

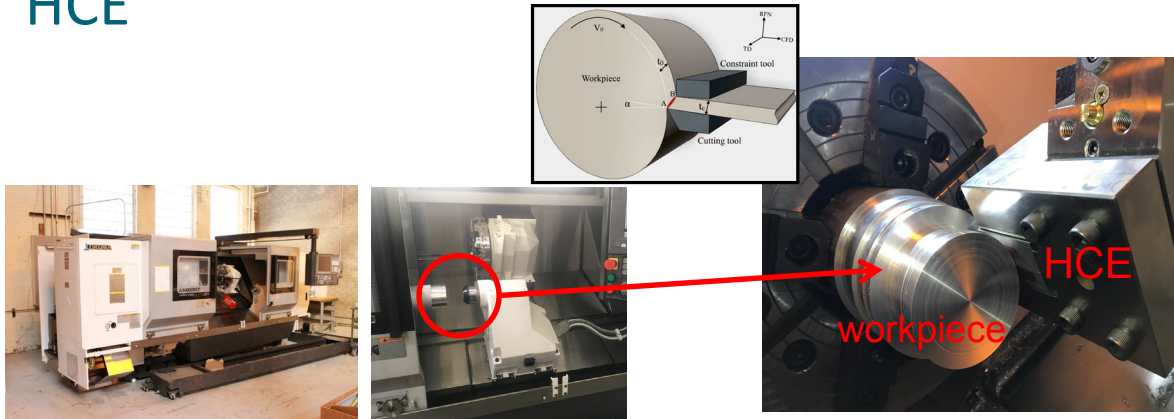
- Scale up shear-based cutting process for producing sheet of low-workability alloys in a single step
- Apply new process to high-Si, low-loss electrical steels (6.5 %Si equivalent performance)
- Enable **cost-effective** production of high-Si electrical steel sheet for increased efficiency of motors



Projected (AMO, 2016) energy saving of $\sim 12,000$ GWh/y (0.44%)

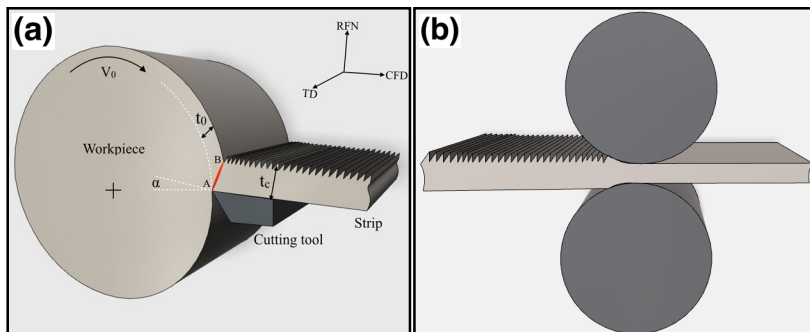
Technical Innovation

HCE



- Scaled production
- Wide range of alloys
- New microstructures
- Transformative technology

Free Machining + Cold Rolling process (FM + CR)



- Alternative process
- Unique benefits

Technical Approach

Phase 1

Small scale HCE

- Fe₄Si, Fe₆Si
- Al alloys, brass
- Background IP

Alloy development – FeSi-X

- Processing in HCE
- Format for workability

Mfg Development

- Equipment/tooling/process
- HCE and FM+CR
- Range of alloys
- New mfg science & IP

Process scaling

Stage 1 scaling: 50mm x 0.3mm

Phase 2

Process scaling – 2 stages

- Equipment design
- Prototype sheet/strip
- Model alloys
- Fe₄Si₄Cr

Process Capability

- Target scale
- Quality
- Material properties
- Processing characteristics

Pre-production

Stage 2A scaling: 100mm x 0.3mm Stage 2B scaling: 150mm x 0.5mm

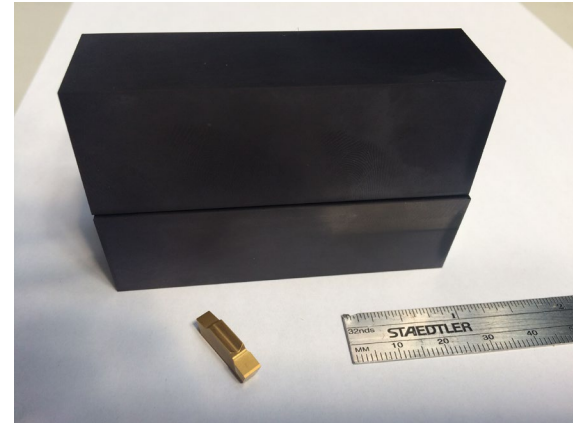
Technical Approach

Risks and unknowns:

- Tool design and performance (e.g., large size carbide tools, edge geometry, life)
- Sheet quality attributes and stampability
- Equipment/workpiece design
- Long industry lead times

Unique execution attributes:

- Prior success in commercializing materials processing technologies (research → product prototyping → commercial adoption)
- M4 Sciences and Purdue.



Large size (first-of-a-kind) carbide HCE tools

Results and Accomplishments

Milestones complete

M1 High-Si alloy development/characterization

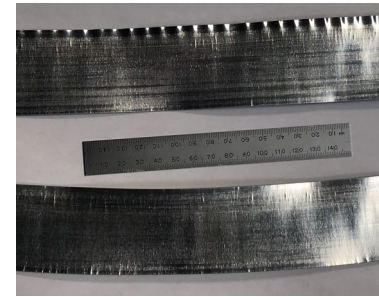
- Fe₄Si₄Cr alloy selected (D1)
- Small-scale HCE strip (to 6 mm x 0.4 mm)
- Stage-1 large cast ingot > forging to workpiece

M2 Stage-1 process: 50-mm strip

- 50-HP machine installed and process prototyped
- 50mm process demonstrated on Al alloy and Brass;
Fe₄Si₄Cr in progress (D2)

Results

- New Fe₄Si₄Cr alloy for process scale-up
- First 50-mm wide HCE and FM+CR strips
- Surface finish < 1 μm Ra/Sa
- Unique microstructure and texture
- Provisional patent and other IP
- Mechanochemical effect discovery (press coverage)



Al6061-T6

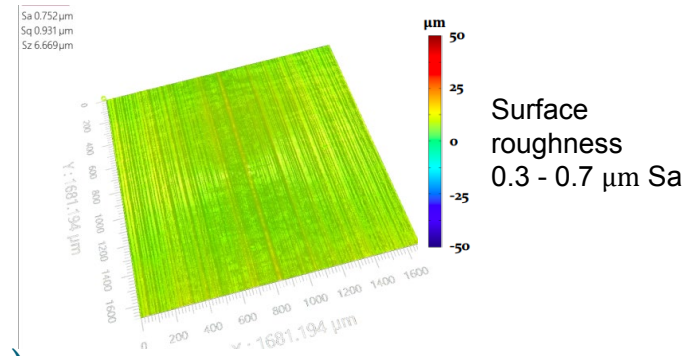


Naval brass

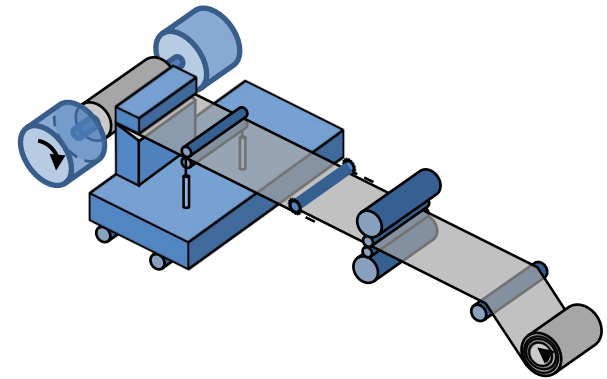
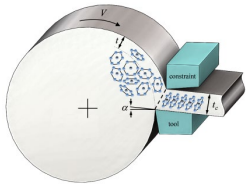
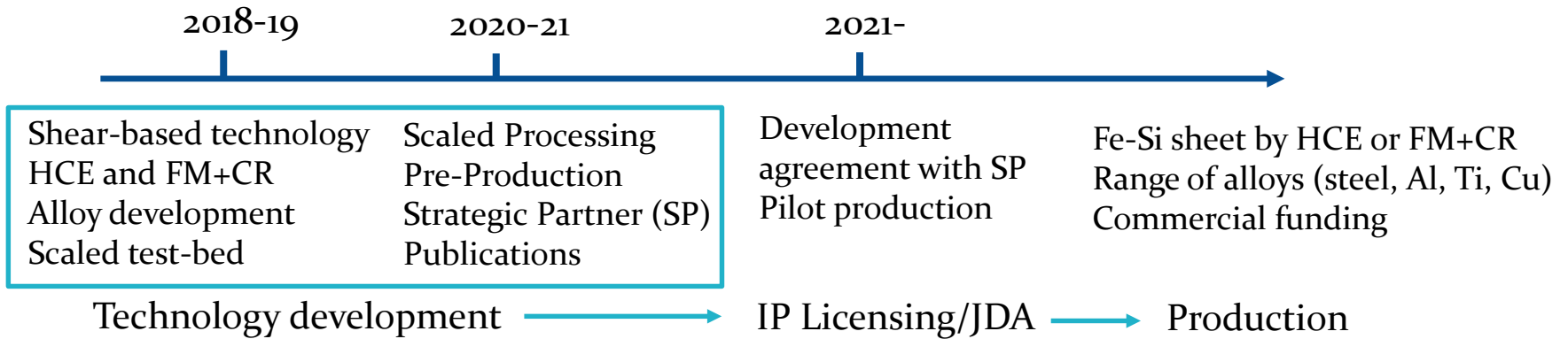
48-mm wide strip



Fe₄Si₄Cr
5-mm wide strip



Transition



Strategy

- Technology development
- Strategic partners – markets engaged early adopters (Seco/Sandvik, General Cable, Spirit)
- IP licensing and commercialization via Purdue/OTC
- Pursue funding for production and commercialization